

Global Leading Company
with **World's Best** Technology

Since **1978**

**GLOBAL
TOP**

LEENO

mirimiri LEENO INDUSTRIAL INC.

DISCLAIMER

All Information about our company's financial outcome in this material were written by Korean International Financial Reporting Standards.

In addition, This material includes information about the future predictions which can be affected by known or unknown risks and uncertainties.

The Future business prospect is supposed to be check. Because, Many such factors such as market situation and business strategy will be important in determining our future results.

Up-to-date our company information is notified in our website. (<https://leeno.com>)

Feel free to contact us with any further questions

Leeno Industrial Inc.

Yongki Choi /CFO +82-51-831-3232

JinCheol Kim/ IR Manager +82-51-831-4931 jckim@leeno.co.kr

CONTENTS

I. Business Description

- 01. About 'LEENO'
- 02. Competitiveness
- 03. Major Clients

II. Our Products

- 01. LEENO PIN
- 02. IC TEST Socket
- 03. Probe Head(Card)
- 04. Secondary Battery Test Pin
- 05. Ultrasonic Wave Probe Component

III. Financial Highlights

- 01. Stock Information
- 02. Year Performance
- 03. Dividend
- 04. Financial statement

Appendix

Global Leading Company
with **World's Best** Technology

Since **1978**
**GLOBAL
TOP**

I . Business Description

01. About 'LEENO'

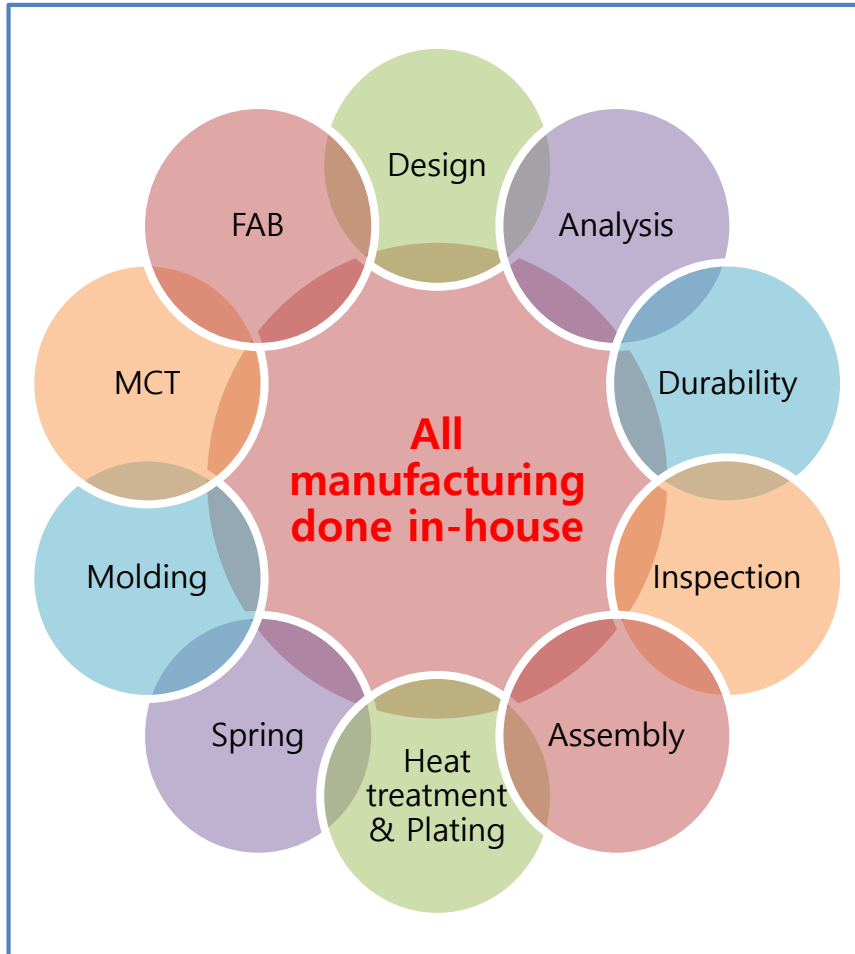
Company Name	Leeno Industrial Inc.	
CEO	Chae-Yoon, Lee	
Foundation	NOV 1978 (Incorporated in DEC 1996)	
Business Category	Manufacture Semiconductor Test Probe and Socket	
Capital Stock	(KRW) 7.62 Billion won ('22)	(KRW) 7.62 Billion won ('23)
Revenue	(KRW) 322.4 Billion won ('22)	(KRW) 255.6 Billion won ('23)
Number of Employees	642 persons ('22)	639 persons ('23)
Head Office Location	10, MIEUMSANDAN-RO 105BEON-GIL, GANGSEO-GU, BUSAN, KOREA	
Homepage	https://leeno.com	

[MAIN HISTORY]

2001.12 Listed on KOSDAQ(058470)
 2003.10 Appointed "Prospective Exporter, Small&Medium Business"
 2004.12 Certified by DAS for ISO 9001
 2004.11 Received an award from Korean prime minister for excellence in regional innovation
 2005.09 Appointed "Excellent Business" and awarded Korea Productivity Award
 2005.11 Awarded "10 Million Dollar Export Achievement Award"
 2006.11 Certified by DAS for ISO 14001
 2007.01 Appointed "Technology Innovative Small and Medium Enterprise"
 2007.07 Awarded "Grand Prize of Small and Medium Business people In Busan"
 2010.01 Concluding a contract to supply the probe for supersonic to Siemens
 2010.11 Awarded "20 Million Dollar Export Achievement Award"
 2012.01 Certified ISO13485
 2013.05 Voted World Class 300
 2013.06 Bonus Issue
 2013.08 Moved in to New extend Head office
 2013.12 Awarded "30 Million Dollar Export Achievement Award"
 2014.03 Awarded "Tin Tower Order of Industrial Service Merit"
 2016.03 Awarded Citation in 'Taxpayer day'
 2016.12 Awarded "50 Million Dollar Export Achievement Award"
 2017.12 Awarded "70 Million Dollar Export Achievement Award"
 2020.02 Completed "NOKSAN Factory" for Medical and Plating part.
 2021.12 Awarded "100 Million Dollar Export Achievement Award"
 2022.12 Awarded "200 Million Dollar Export Achievement Award"
 2023.12 Certified ISO45001

02. Competitiveness

• World Class Manufacturing



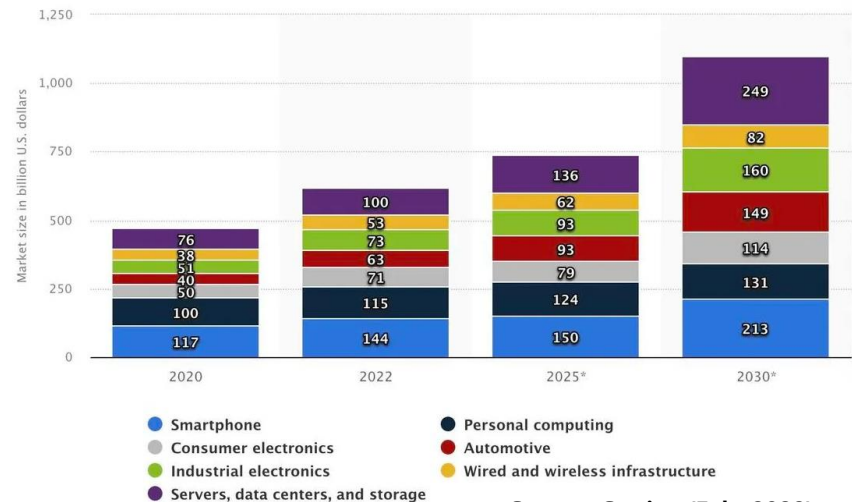
• Consistent, Quality Products



03. Major Clients



■ Semiconductor market size worldwide from 2020 to 2030, by application (units : billion U.S. dollars)



Semiconductor market size worldwide by application will total 1,098 billion dollars in 2030, according to Statista. In addition, smartphone(213 billion dollars), Servers & data centers & storage(249 billion dollars), Personal computing(131 billion dollars), Automotive(149 billion dollars), Industrial electronics(160 billion dollars), Consumer electronics(114 billion dollars) and Wired & wireless infrastructure(82 billion dollars) is expected to growth in 2030.

According to Current Trend and The Fourth Industrial Revolution(such as IoT, AI, 5G, VR, AR, Big-data, Metaverse, Automatic Driving & Electronic Car), As types and functions of non-memory and memory semiconductors go into The Devices is diversifying, Demands for functions and characteristics in Semiconductor testing market is increasing. LEENO will be accompanied by the growth of the new IT market, to actively participate in the needs of the semiconductor test market with LEENO PIN and IC TEST SOCKET.

II. OUR PRODUCTS

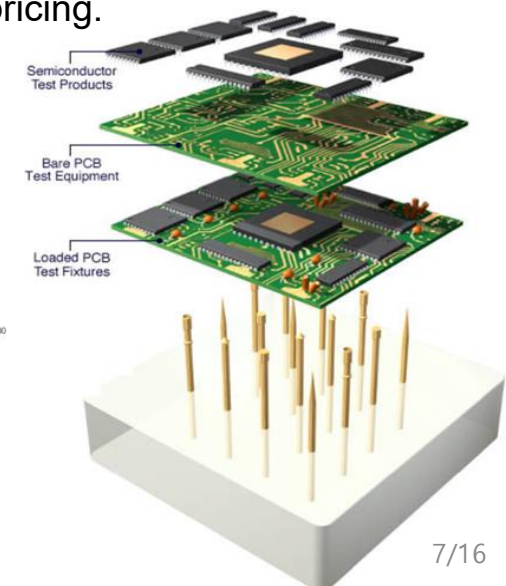
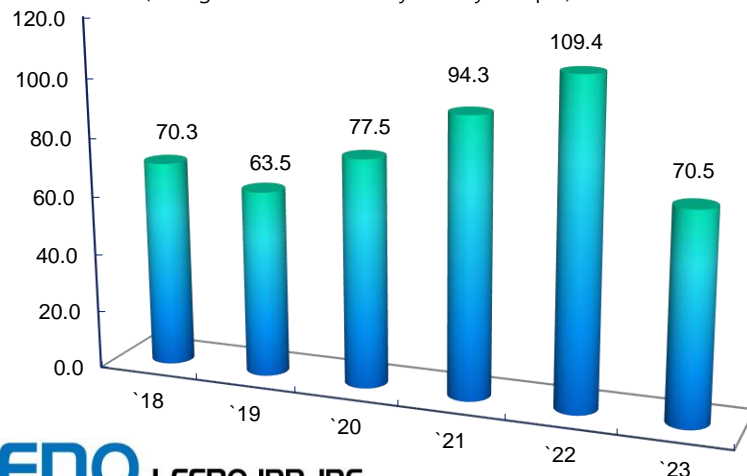
01. LEENO PIN

- Contact with electronic equipment and PCB circuit to check whether properly to make or not
- LEENO PIN is our own-brand as test probe pin, and about 990 companies(Based on sales of 2023) are using 'LEENO PIN'
- Recently, Along with high demand of Fine Pitch Probe with variety of electronic equipment, we are satisfied our customer's needs providing high quality and competitive pricing.

Sales amount

(UNIT : KRW bil)

LEENO PIN(with goods and secondary battery test pin)



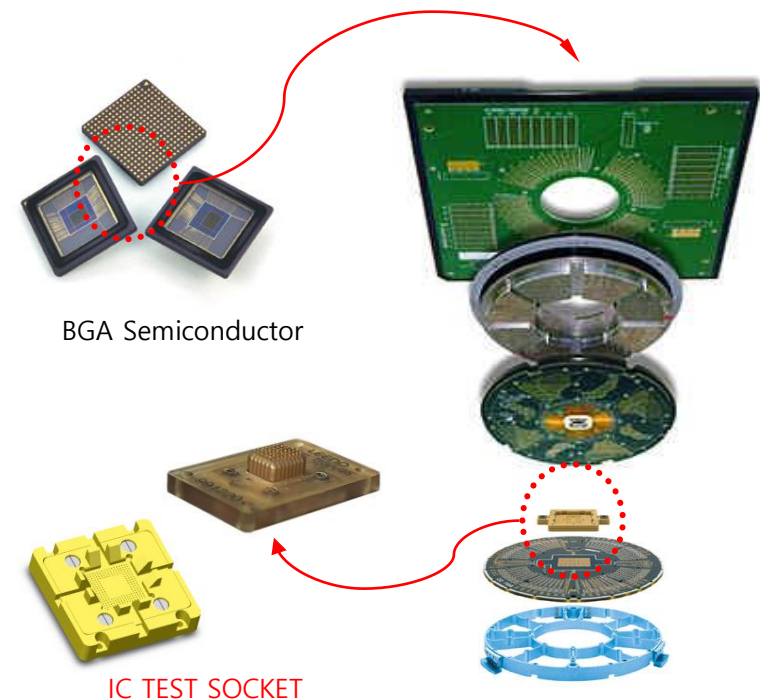
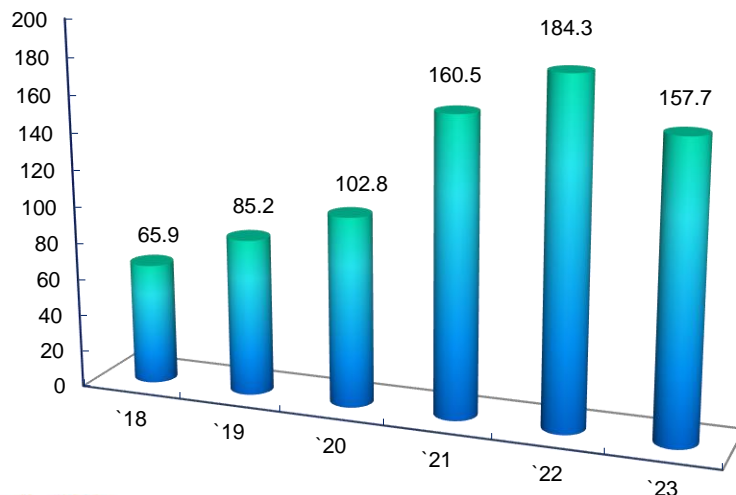
02. IC TEST SOCKET

- IC Test socket has been used to test memory and non-memory IC semiconductor. The purpose of this is to test electrical signal after contacting package which is located in test socket.
- Our innovative vertical type in IC test socket has been commercialized for 20 years through out developing innovative technology

■ Sales amount

IC TEST SOCKET(with probe card)

(UNIT : KRW bil)

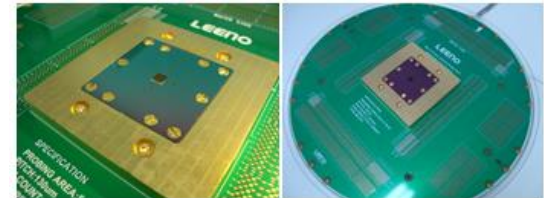


03. PROBE HEAD(CARD)

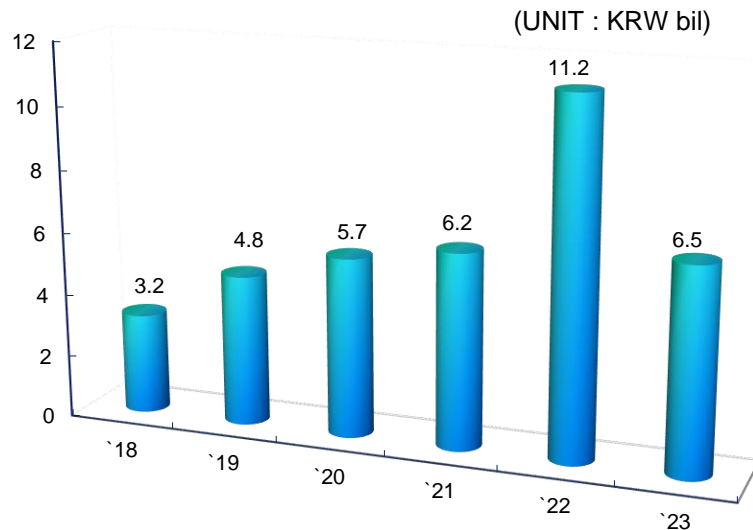
- The whole process semiconductor inspection equipment to test electrical characteristics in separated chips in wafer.
- LEENO is the best leading technology company to provide solution in competitive accelerating and evolved test market.
 - Long life Cycle
 - Quick Delivery
 - High Speed
 - Low Cost

Semiconductor whole process (FAB)

Wafer level test (LEENO PROBE CARD)



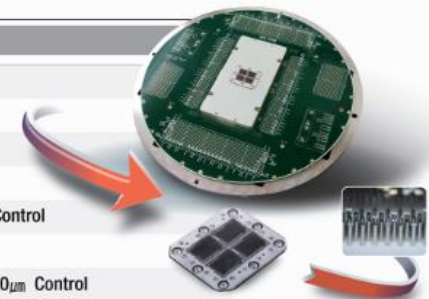
Sales amount



Wafer Level CSP/TSV Probe Card

150 μ m Pitch Flip Chip Quad Site Vertical Probe Card Total 13,500Pin

Specification	
Minimum Pitch	120 μ m
Planarity	$\leq 30\mu$ m
Probe Alignment	$\leq \pm 12\mu$ m
Scrub Mark	0~5 μ m
Tip Length	100 μ m~500 μ m $\pm 10\mu$ m Control
Temperature	-20 $^{\circ}$ C~120 $^{\circ}$ C
Probe Depth	6,900 μ m~12,000 μ m $\pm 200\mu$ m Control
Contact Resistance	$\leq 0.5\Omega$
Probe Tip Diameter	10 μ m~100 μ m Control
Pin Force	2.5g / Mil
Tip Material	Be-Cu(Au Plate) / Pd Alloy



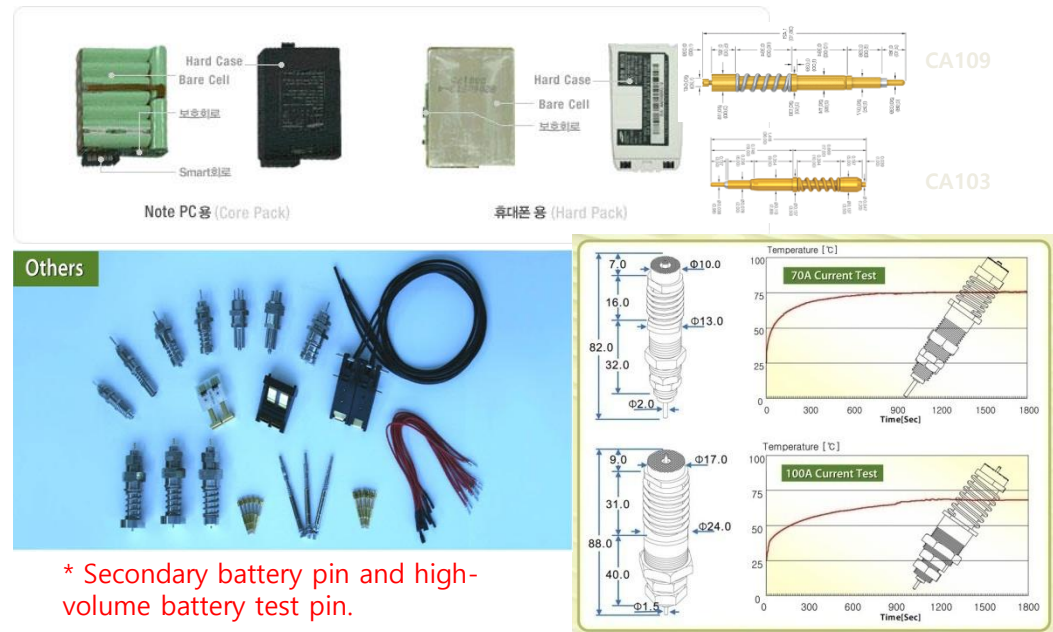
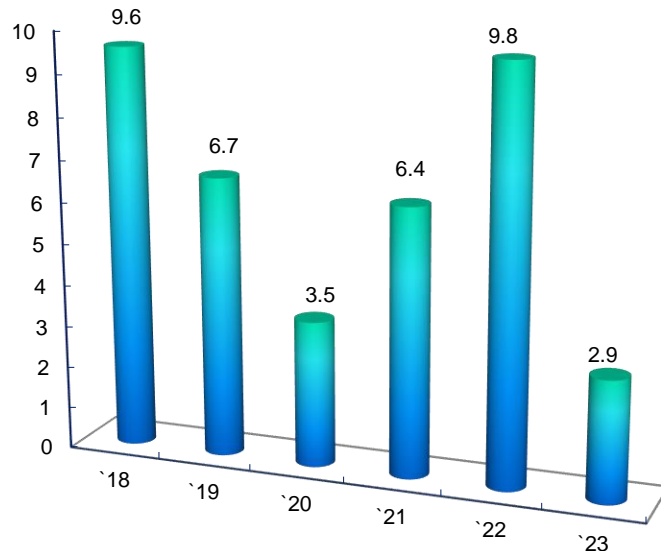
2012" 1Q	
Pin Count	20,000pin
Minimum Pitch	120 μ m

04. Secondary Battery Test Pin

- The demand for secondary batteries to be used for key items in the IT sector such as portable products is expected to increase more compared with the previous year.
- LEENO manufacture high-current test pin for hybrid car to cope with active market.
- World-class technology and pin production experience in domestic market make possible for the final customer to use secondary battery safely.

Sales amount

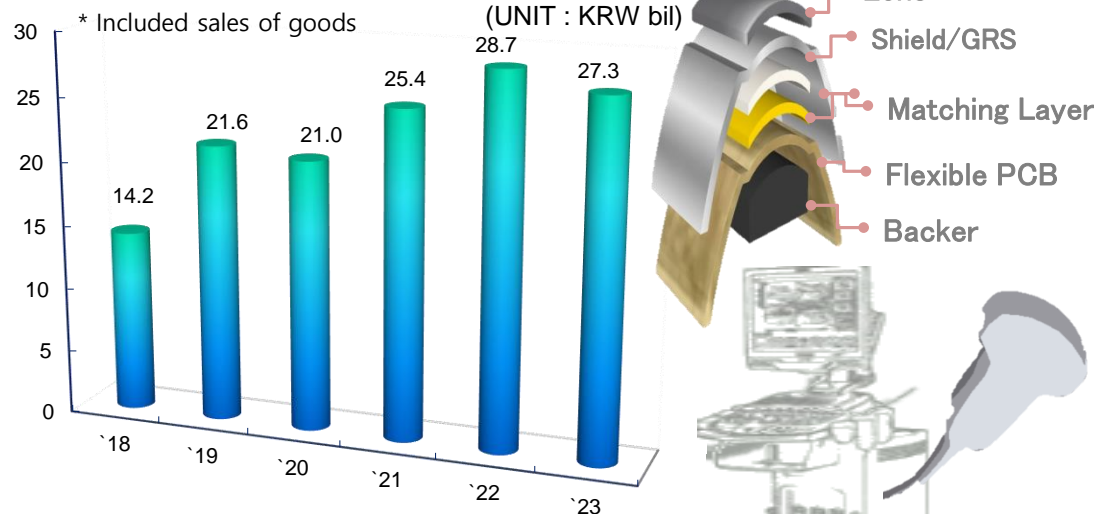
(UNIT : KRW bil)



05. Ultrasonic wave probe component

- 25th Jan, 2010 LEENO Industrial Inc. makes an agreement about supplying Ultrasonic wave probe component with SIEMENS
 - What is the 'Ultrasonic wave probe' ? : It is single unit machine of ultrasonic diagnostic imaging device which has function to generate and detect ultrasonic wave and contacted directly with human body.
(※ Regarded as a consumable parts in ultrasonic wave diagnostic device)
- This will be a base for new growth of LEENO's new market
- Manufacture the core part of probe, developing high value

Sales amount



Lens

- This part is contacted with human body directly and control ultrasonic wave's direction.

Shield

- To remove noise from ultrasonic wave probe and for electrical grounding and shielding role.

Matching Layer

- To control and magnify ultrasonic wave's direction in the ultrasonic wave probe.

Flexible PCB

- The component for applied and received voltage.

Backer

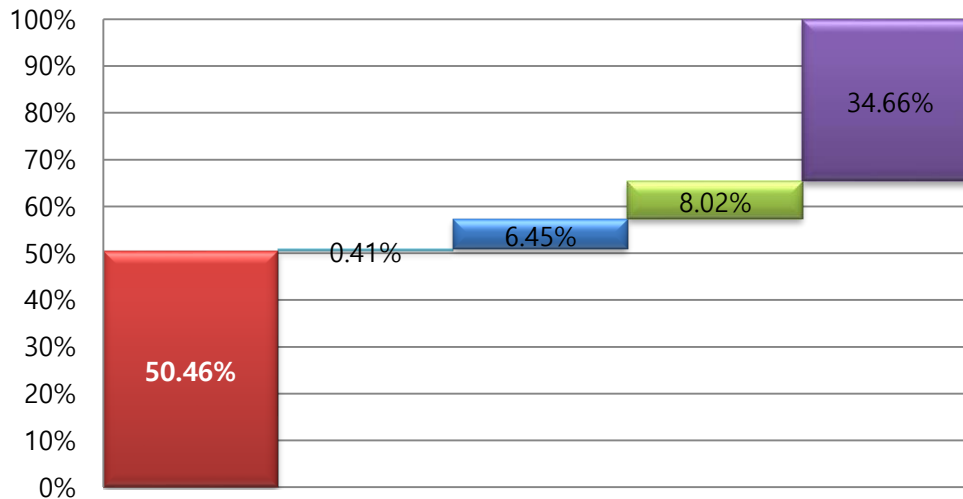
- This part absorbs the backside direction's ultrasonic wave which was generated from ultrasonic wave probe.

III. Financial Highlight

01. Stock Information

- LEENO is doing our best to enhance the company's value in return for your trust and encouragement.

Total stocks: 15,242,370
Treasury stocks : 63,250
Capital stock :
7,621,185,000 (KRW)



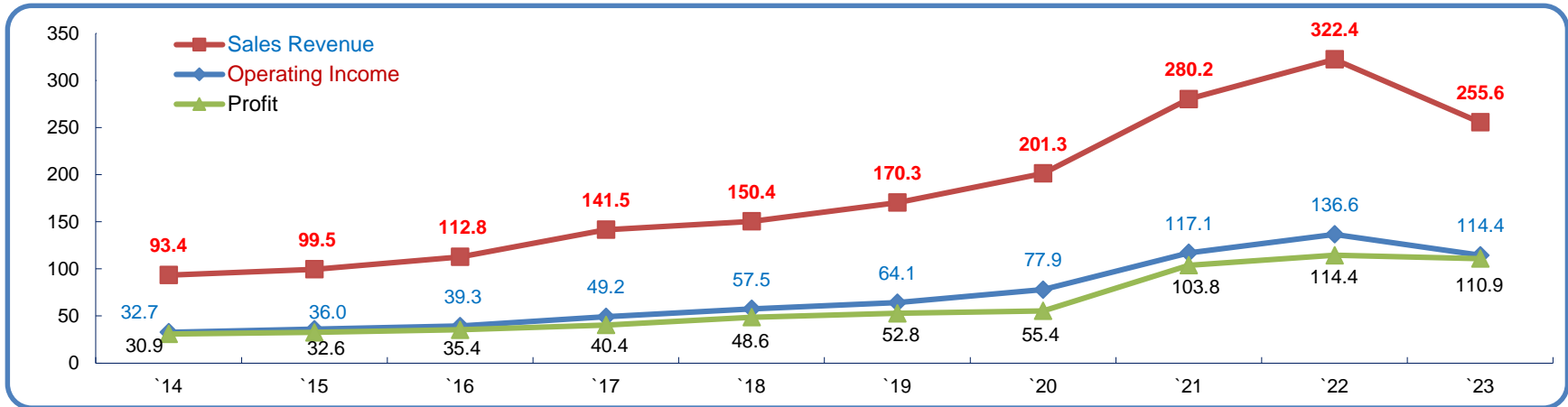
- CEO(CHAE-YOON, LEE) 5,283,669 (34.66%)
- Wasatch Advisors 1,223,169 (8.02%)
- National Pension Service 982,494주(6.45%)
- Treasury stock 63,250 (0.41%)
- Other 7,689,788 (50.46%)

- Based on Stockholding status Report by National Pension Service(At AUG 7TH, 2023), Wasatch Advisors, Inc (At JAN 10th, 2024)
- According to Treasury stock, Please find the Disclosure of Treasury stock at NOV 29th, 2019.

02. Year Performance

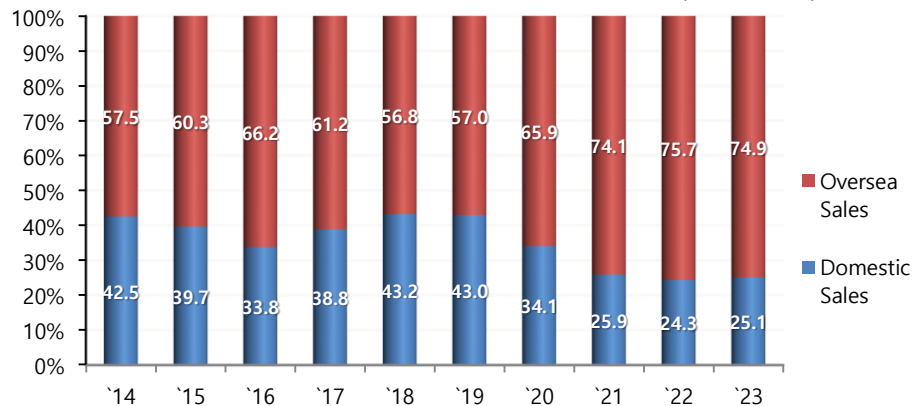
● Year Performance

(UNIT : KRW bil)



● Export Ratio

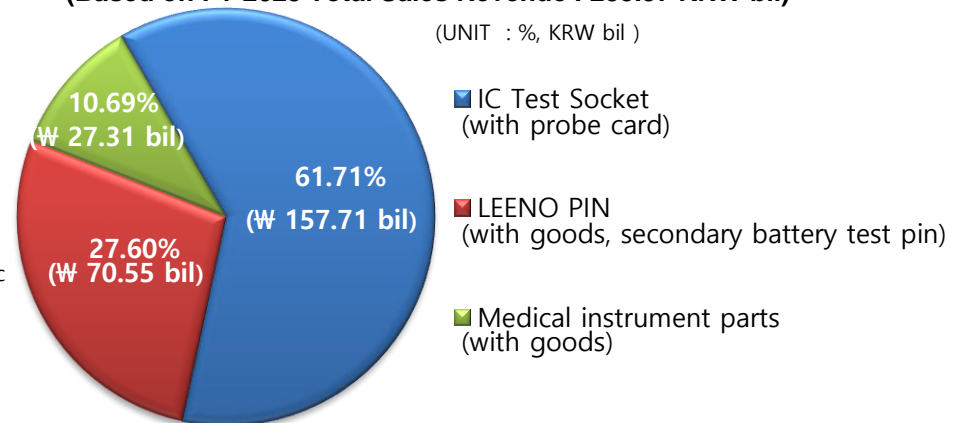
(UNIT : %)



● Revenue Ratio

(Based on FY 2023 Total Sales Revenue : 255.57 KRW bil)

(UNIT : %, KRW bil)



03. Dividend

● Dividend

(UNIT : KRW)

Date	Par value	Net income	Earning Per Share (EPS)	Dividend	Dividend yield ratio(%)	Total Dividend amount
`23(E)	500	110,923,015,440	7,308	3,000	1.48	45,537,360,000
`22	500	114,363,791,327	7,534	3,000	1.85	45,537,360,000
`21	500	103,805,815,149	6,839	2,500	1.26	37,947,800,000
`20	500	55,378,772,170	3,648	1,500	1.14	22,768,680,000
`19	500	52,790,182,377	3,485	1,200	1.87	18,214,944,000

- About the Dividend in 2019~2023, Total Dividend amount for 15,179,220 stocks except Treasury stocks(63,250).
- About the Dividend in 2018, Total Dividend amount for 15,143,220 stocks except Treasury stocks(99,150).

Stable Management

- Superior Financial structure and cashable property
- No-borrow Management & Maintenance
- Increasing of operating profit & Net income
- Maintenance of profit from high added value



Policy for Stockholders

04. Financial Statement

● Balance Sheet

(UNIT : KRW)

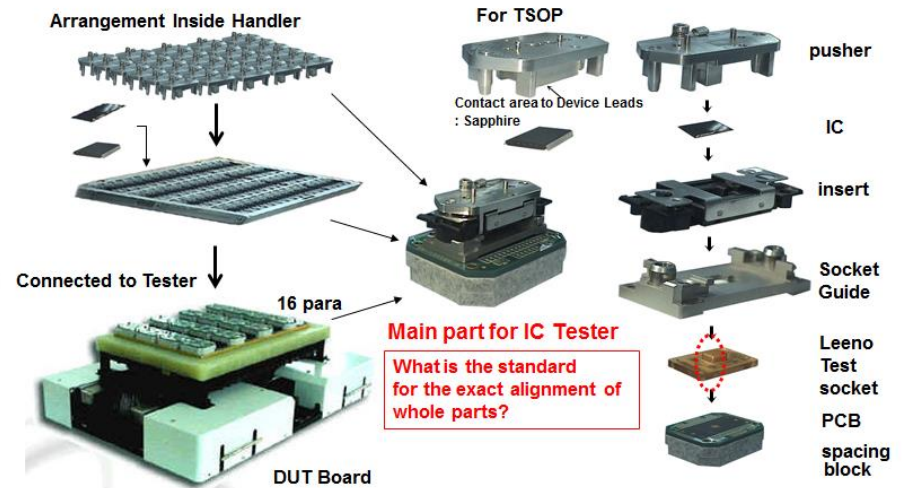
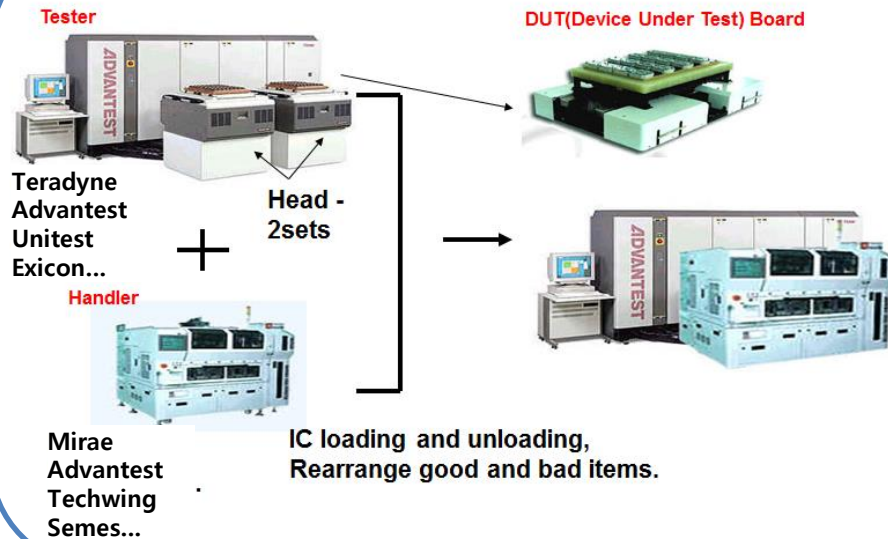
	FY 2023	FY 2022
I . Current Assets	372,372,898,847	377,024,805,599
II. Non-Current Assets	210,496,566,447	154,463,323,833
Total Assets	582,869,465,294	531,488,129,432
I . Current Liabilities	23,110,842,940	36,383,168,010
II. Non-current Liabilities	2,684,424,288	1,921,378,596
Total Liabilities	25,795,267,228	38,304,546,606
I . Issued capital	7,621,185,000	7,621,185,000
II. Capital Surplus	5,601,810,444	5,601,810,444
III. Other Capital Adjustments	(2,353,516,350)	(2,353,516,350)
IV. Retained Earnings	546,204,718,972	482,314,103,732
Total Equities	557,074,198,066	493,183,582,826
Total Equities and Liabilities	582,869,465,294	531,488,129,432

● Statement of comprehensive income (Accumulated)

(UNIT : KRW)

	FY 2023	FY 2022
I . Revenue (Sales)	255,573,034,656	322,422,803,089
II. Cost of sales	127,238,409,519	167,794,521,227
III. Gross Profit	128,334,625,137	154,628,281,862
IV. Selling General Administrative Expenses	13,956,224,846	17,993,551,880
V . Operating Income	114,378,400,291	136,634,729,982
VI. Non-operating Income	27,865,067,804	17,440,784,590
VII. Profit before tax	142,243,468,095	154,075,514,572
VIII. Income tax expense	31,320,452,655	39,711,723,245
IX. Profit	110,923,015,440	114,363,791,327
X . Other comprehensive Income	(1,495,040,200)	(935,595,604)
XI . Total comprehensive Income	109,427,975,240	113,428,195,723
XII . Basic Earnings per share	7,308	7,534

APPENDIX



THANK YOU

